

11-30-2000

Docket No.: 55400

U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office



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101533155

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof

1. Name of conveying party(ies):

Chih-Shun CHEN
Chao-Dung SUO
Jui-Meng JAO
Ke-Chuan YANG
Feng-Lung CHIEN

Additional names(s) of conveying party(ies)

☐ Yes ☒ No

2. Name and address of receiving party(ies):

Siliconware Precision Industries
Name: **Co., Ltd.**

Address: **No. 123, Sec. 3, Da Fong Road**

Tantzu

3. Nature of conveyance:

☒ Assignment

☐ Merger

☐ Security Agreement

☐ Change of Name

☐ Other

City: **Taichung** State/Prov.:

Country: **Taiwan, R.O.C.** ZIP:

Execution Date: **July 25, 2000**

Additional name(s) & address(es)

☐ Yes ☒ No

4. Application number(s) or registration numbers(s):

9/709908

If this document is being filed together with a new application, the execution date of the application is: **July 25, 2000**

Patent Application No.

Filing date

B. Patent No.(s)

Additional numbers

☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: **Peter F. Corless**

Registration No. **33,860**

Address: **EDWARDS & ANGELL, LLP**

Dike, Bronstein, Roberts & Cushman, IP Group

130 Water Street

City: **Boston** State/Prov.: **MA**

Country: **U.S.A.** ZIP: **02109**

6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 3.41):.....\$ **40.00**

☒ Enclosed - Any excess or insufficiency should be credited or debited to deposit account

☐ Authorized to be charged to deposit account

8. Deposit account number:

04-1105

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Peter F. Corless

Name of Person Signing

Signature

Date

11/8/2000

Total number of pages including cover sheet, attachments, and

2
PATENT

REEL: 011278 FRAME: 0256

ASSIGNMENT OF U.S. PATENT APPLICATION

In consideration of the sum of One Dollar (\$1.00) in hand paid, and other good and valuable consideration, the receipt of which is hereby acknowledged, the undersigned

Inventor(s) (1) Chih-Shun CHEN. (2) Chao-Dung SUO. (3) Jui-Meng JAO. (4) Ke-Chuan YANG.
Full Name(s) (5) Feng-Lung CHIEN

hereby sell, assign and transfer to

Assignee Name and Address
SILICONWARE PRECISION INDUSTRIES CO., LTD.
No. 123, Sec. 3, Da Fong Rd., Tantz, Taichung, Taiwan, R.O.C.

(hereinafter called the Assignee) the entire right, title, and interest in and to any and all improvements which are disclosed in the Application for United States Letters Patent entitled

Title of Invention
METHOD OF FABRICATING SOLDER BUMPS WITH HIGH COPLANARITY FOR FLIP-CHIP APPLICATION

which application was

Complete either a) or b)
a) executed by the undersigned on the day of , 19
b) filed on the day of , 19

Serial No
including any and all United States Letters Patents which may be granted therefore and any and all extensions, divisions, reissues, substitutes, renewals or continuations thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property.

It is hereby authorized and requested that the Commissioner of Patents issue any and all of said Letters Patent, when granted, to said Assignee.

Further, it is agreed that, when requested, without charge to but at the expense of said Assignee, the undersigned will execute all divisional, continuing, substitute, renewal, and reissue patent applications; execute all rightful other papers; and generally do everything possible which said Assignee shall consider desirable for aiding in securing and maintaining proper patent protection.

Date Signed at Tantz, Taichung
this . 25th day of July , 2000

Inventor(s) Full Signature(s)
INVENTOR(S):
Chih-Shun CHEN
Chao-Dung SUO
Jui-Meng JAO
Ke-Chuan YANG
Feng-Lung CHIEN

Witnesses' Full Signatures
WITNESSES: